### **SCOPE:**

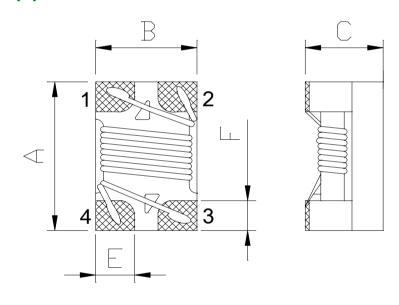
This specification applies to the Pb Free Signal Common mode filters for MWCU-201212H1-SERIES

### PRODUCT INDENTIFICATION

### MWCU- 201212 H1 - 900

- 1
- 2
- 4
- **1** Product Code
- 2 Dimensions Code
- 3 Signal For AECQ-200
- **4** Inductance Code

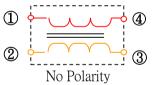
# (1) SHAPES AND DIMENSIONS



- A: 2.05±0.20 mm
- B: 1.25±0.20 mm
- C: 1.20±0.20 mm
- E: 0.50 Typ. mm
- F: 0.40 Typ. mm

### **SCHEMATIC**

Equivalent circuit



# (2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

**TEST INSTRUMENTS** 

L/Z : HP 4291B IMPEDANCE ANALYZER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

I.R : CHROMA MODEL 19073 AC/DC/IR HIPOT TESTER (or equivalent)

# (3) CHARACTERISTICS

(3)-1 Operate temperature range ......  $-40^{\circ}$ C  $\sim +125^{\circ}$ C (Including self temp. rise)



### **TABLE 1**

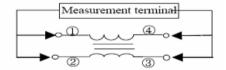
MAGLAYERS PT/NO.	Z(Ω) Impedance @100MHz	RDC (Ω) max. (1 line)	Rated Voltage Vdc(V)	ldc Max.(mA)	Withstand Voltage (V)	Insulation Resistance (MΩ)Min.
MWCU-201212H1-300	30±25%	0.20	50	450	125	10
MWCU-201212H1-670	67±25%	0.25	50	400	125	10
MWCU-201212H1-750	75±25%	0.30	50	360	125	10
MWCU-201212H1-900	90±25%	0.35	50	330	125	10
MWCU-201212H1-121	120±25%	0.30	50	400	125	10
MWCU-201212H1-161	160±25%	0.35	50	350	125	10
MWCU-201212H1-181	180±25%	0.35	50	330	125	10
MWCU-201212H1-201	200±25%	0.35	50	330	125	10
MWCU-201212H1-221	220±25%	0.35	50	310	125	10
MWCU-201212H1-261	260±25%	0.40	50	300	125	10
MWCU-201212H1-301	300±25%	0.40	50	290	125	10
MWCU-201212H1-361	360±25%	0.45	50	280	125	10
MWCU-201212H1-371	370±25%	0.45	50	280	125	10
MWCU-201212H1-501	500±25%	0.55	50	170	125	10
MWCU-201212H1-671	670±25%	0.60	50	140	125	10
MWCU-201212H1-901	900±25%	0.60	50	80	125	10

※ IDC: Based on temperature rise (△T: 40°C Typ.)

### **TEST EQUIPMENT**

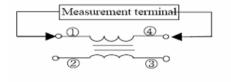
1. Impedance / Inductance

Measured by HP 4291B RF Impedance Analyzer.



### 2. DC Resistance

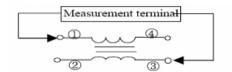
Measured by Chroma 16502 mill ohm meter



### 3. Insulation Resistance

Measured by Chroma 19073

Measurement voltage: 50v, Measurement time: 3 sec.





# (4) RELIABILITY TEST METHOD

Item	Specifications	Test conditions			
Solder ability	It can be connected on the	Apply cream solder to the test circuit board .			
	Recommendation soldering condition.	It is mounted on the recommendation soldering condition.			
		Dip pads in flux and dip in solder pot ( 96.5 Sn/3.5 Ag			
		solder) at 260°C ±5°C.			
Terminal	The terminal electrode and the ferrite	Solder a chip to test substrate , and then laterally			
strength	must not be damaged.	apply a load 0.5Kg in the arrow direction.			
		Test Board			
	The terminal electrode and the ferrite	Soldering a chip to a test substrate ,			
	must not be damaged.	bend the substrate by 2mm and then return.			
Strength on	40 45 45 45 45 45 45 45 45 45 45 45 45 45				
pc board bending	Force Dimensions in mm				
	Test board : Glass base epoxy multiplayer board pc board pattern.				
	PC board pattern : Recommended PC board pattern.				



# (4) RELIABILITY TEST METHOD

# Mechanical

Item	Specifications	Test conditions		
Board Flex	The forces applied on the right conditions must not damage the terminal electrode and the ferrite.	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 60 sec		
Terminal Strength	The chip must not damage the terminal electrode and the ferrite.	Appendix 1 Note(AEC-Q200-005):Force of 1.8 kg for 60 seconds.		
Solderability	The electrodes shall be at least 95% covered with new solder coating.	Pre-heating: 150℃, 1min Solder Composition: Sn/3.0Ag/0.5Cu Solder Temperature: 245±5℃ Immersion Time: 4±1sec		
Resistance to Soldering Heat	Appearance:No damage Inductance change shall be within ±20%.	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5 Solder Temperature: 260±5℃ Immersion Time: 10±1sec		
Resistance to Solvents	There must be no change in appearance or obliteration of marking.	Inductors must withstand 6 minutes of alcohol or water.		
Mechanical Shock	The forces applied on the right conditions must not damage the terminal electrode and the ferrite.	Pulse shape: Half-sine waveform Impact acceleration: 100 g Pulse duration: 6 ms Number of shocks: 18 shocks (3 shocks for each face) Orientation: Bottom, top, left, right, front and rear faces		
Vibration	Appearance:No damage Inductance change shall be within ±20%.	Vibration waveform: Sine waveform Vibration frequency: 10Hz~2000Hz Vibration acceleration: 5g Sweep rate: 0.764386otcave/minute Duration of test: 12 cycles each of 3 orientations 20 minutes for each cycle Vibration axes: X, Y & Z		



# (4) RELIABILITY TEST METHOD Environmental

Item	Specifications	Test conditions		
		Temperature: 125±3℃		
High Temperature Exposure (Storage)		Time: 1000hrs		
		Measured after exposure in the room condition		
		for 24hrs		
		Temperature: 125±2℃		
1		Appliend Current : Rated Current		
Operational Life		Time: 1000± 24 hrs		
		Measured after exposure in the room condition		
		for 24hrs		
	Appearance:No damage (for microscope of CASTOR	Temperature: 85±2℃		
		Relative Humidity: 85%		
Biased Humidity		Time: 1000hrs		
		Measured after exposure in the room condition		
		for 24hrs		
Temperature Cycling	MZ-420X)Inductance change shall be within ±20%.	Total cycles: 1000 cycles Temperature Cycling Test Conditions : -50 to +125 ℃ Soak Mode Condition : 30 minutes Measured after exposure in the room condition for 24hrs		
ECD		Test mode: Contact Discharge Discharge level: ±6KV, Discharge interval: 1 second Polarity of the output voltage: Positive and negative Number of discharge: Discharge +/- for 1 time for the 2 test points.		
ESD		Test Mode: Air Discharge Discharge level: ±12KV, ±16KV, ±25KV Discharge interval: <5 seconds Polarity of the output voltage: Positive and negative Number of discharge: Discharge +/- for 1 time for the 1~2 test points.		

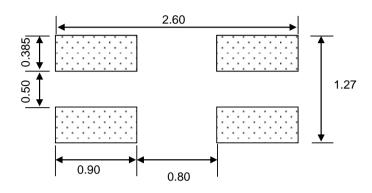


### (5) RECOMMENDED SOLDERING CONDITIONS

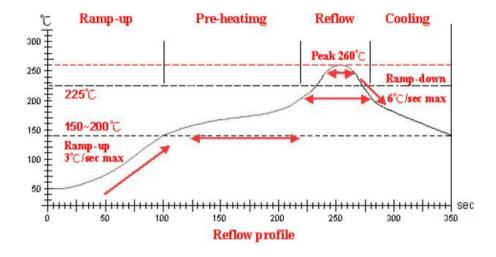
(Please use this product by reflow soldering)

### (5)-1 RECOMMENDED FOOTPRINT

Unit: mm



## (5)-2 RECOMMENED REFLOW PATTERN



Lead-Free(LF) Refer to J-STD-020C

Item	Ramp-up	Pre-heating	Reflow	Peak Temp.	Cooling
Temp. scope	R.T.~150℃	150℃~200℃	<b>225</b> ℃	<b>260±5</b> ℃	Peak Temp.~150°C
Time result		60~180 Sec.	20~60 Sec.	5~10 Sec.	

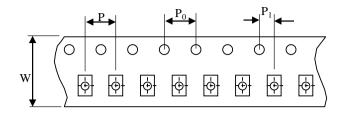
### NOTE:

- 1. Re-flow possibile times:with in 2 times
- 2. Nitrogen adopted is recommended while in re-flow



# (6) PACKAGING

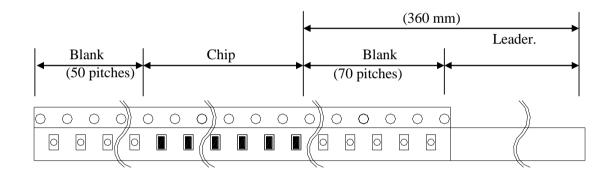
## (6)-1 CARRIER TAPE DIMENSIONS (mm)



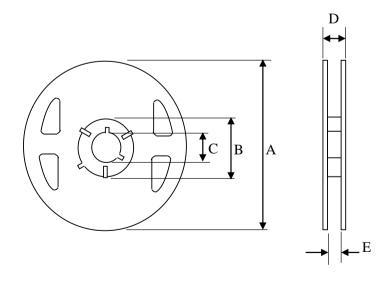
W: 8.0 mm
P: 4.0 mm
P0: 4.0 mm
P1: 2.0 mm

### (6)-2 TAPING DIMENSIONS (mm)

There shall not continuation more than two vacancies of the product.



### (6)-3 REEL DIMENSIONS



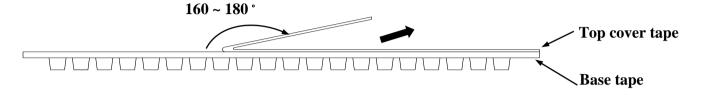
A: 180 mm
B: 60 mm
C: 13.5 mm
D: 15.5 mm
E: 9.0 mm

## (6)-4 COVER TAPE PEEL STRENGTH

The force for tearing off cover tape is  $0.1\sim0.6(N)$  in the arrow direction at the following conditions:

Temperature : 5 ~ 35℃ Humidity : 45 ~ 85%

Atmospheric pressure: 860 ~ 1060 hpa



### (6)-5 QUANTITY

2000 pcs/Reel

### (6)-6 The products are packaged so that no damage will be sustained.

### (7) ATTENTION IN CASE OF USING

In case of using product ,please avoid following matters:

Splashing water or salt water

**Dew condenses** 

Toxic gas (Hydrogen sulfide, Sulfurous acid ,Chlorine, Ammonia)

Vibrations or shocks which exceed the specified condition

Please be careful for the stress to this product by board flexure or something after the mounting.

Please note that the contents may change without any prior notice due to reasons such as upgrading.

